

AN INTEGRATED BACK-END INTEGRATED CIRCUIT MANUFACTURING
ASSEMBLY

ABSTRACT OF THE DISCLOSURE

- 5 An integrated back-end integrated circuit (IC) manufacturing assembly is disclosed. In one embodiment, the present invention has a front-of-line portion comprising a plurality of integrated sub-stations for operating on a first plurality of die-strips on an in-line basis to produce a second plurality of die-strips. The present embodiment further comprises an end-of-line portion coupled to the front-of-line portion and
- 10 comprising a plurality of integrated sub-stations for operating on the second plurality of die-strips on an in-line basis to produce die-strip components. The present embodiment also comprises an in-line test portion coupled to the end-of-line portion for testing the die-strip components. The present embodiment further comprises a finish portion coupled to the in-line test portion and comprising a plurality of integrated sub-stations operating on tested die-strip components. In addition, camera systems perform automated visual inspection of dies on the die-strip and maintain a database that can be used for automated reject management.
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